

HiPerFRED

 V_{RRM} 1200 V

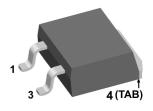
12 A I FAV

35 ns

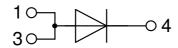
High Performance Fast Recovery Diode Low Loss and Soft Recovery Single Diode

Part number

DSEP12-12BZ



Backside: cathode



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: TO-263 (D2Pak-HV)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Terms _Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact the sales office, which is responsible for you.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the product in aviation, in health or live endangering or life support applications, please notify. For any such application we urgently recommend

- to perform joint risk and quality assessments; the conclusion of quality agreements;
- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747 and per semiconductor unless otherwise specified

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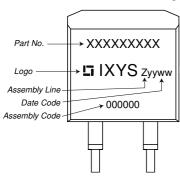


Fast Diode				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V _{RSM}	max. non-repetitive reverse blocki	ng voltage	$T_{VJ} = 25^{\circ}C$			1200	V
V _{RRM}	max. repetitive reverse blocking ve	oltage	$T_{VJ} = 25^{\circ}C$			1200	V
I _R	reverse current, drain current	V _R = 1200 V	$T_{VJ} = 25^{\circ}C$			100	μΑ
		$V_R = 1200 V$	$T_{VJ} = 150$ °C			0.5	mΑ
V _F	forward voltage drop	I _F = 15 A	$T_{VJ} = 25^{\circ}C$			3.25	V
		$I_F = 30 A$				3.96	٧
		I _F = 15 A	T _{VJ} = 150°C			2.06	٧
		$I_F = 30 A$				2.89	٧
I _{FAV}	average forward current	T _C = 130°C	T _{vJ} = 175°C			12	Α
		rectangular $d = 0.5$					
V _{F0}	threshold voltage		$T_{VJ} = 175$ °C			1.00	٧
r _F	slope resistance	ess calculation only				55	mΩ
R _{thJC}	thermal resistance junction to case	9				1.6	K/W
thCH	thermal resistance case to heatsin	ık			0.25		K/W
P _{tot}	total power dissipation		$T_{C} = 25^{\circ}C$			95	W
I _{FSM}	max. forward surge current	$t = 10 \text{ ms}$; (50 Hz), sine; $V_R = 0 \text{ V}$	$T_{VJ} = 45^{\circ}C$			90	Α
C¹	junction capacitance	$V_R = 600 V$ f = 1 MHz	$T_{VJ} = 25^{\circ}C$		5		pF
I _{RM}	max. reverse recovery current		$T_{VJ} = 25 ^{\circ}\text{C}$		14		Α
		$I_F = 15 \text{ A}; V = 800 \text{ V}$	$T_{VJ} = 125$ °C		23		Α
t _{rr}	reverse recovery time	$\begin{cases} I_F = 15 \text{ A}; V = 800 \text{ V} \\ -d_F/dt = 500 \text{ A}/\mu\text{s} \end{cases}$	$T_{VJ} = 25 ^{\circ}\text{C}$		70		ns
			$T_{VJ} = 125$ °C		300		ns



Package TO-263 (D2Pak-HV)				Ratings			
Symbol	Definition Conditions		min.	typ.	max.	Unit	
I _{RMS}	RMS current per terminal				35	Α	
T _{VJ}	virtual junction temperature		-55		175	°C	
T _{op}	operation temperature		-55		150	°C	
T _{stg}	storage temperature		-55		150	°C	
Weight				1.5		g	
F _c	mounting force with clip		20		60	N	
d _{Spp/App}	creepage distance on surface striking distance through air	terminal to terminal	4.2			mm	
$d_{\text{Spb/Apb}}$	creepage distance on surface striking distance through all	terminal to backside	4.7			mm	

Product Marking



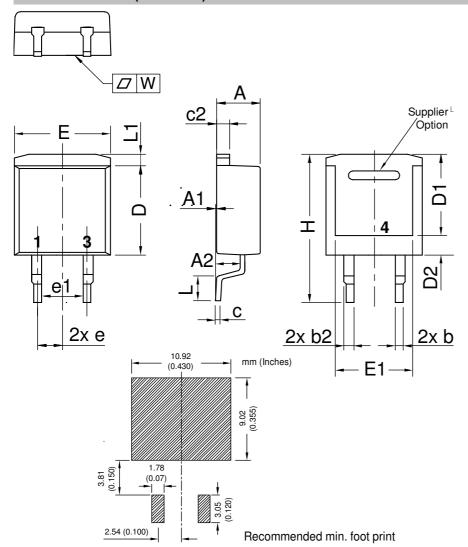
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSEP12-12BZ	DSEP12-12BZ	Tape & Reel	800	514454

Similar Part	Package	Voltage class	
DSEP12-12AZ	TO-263AB (D2Pak) (2HV)	1200	

Equivalent Circuits for Simulation			* on die level	$T_{VJ} = 175 ^{\circ}\text{C}$
$I \rightarrow V_0$)— <u>R</u> o	Fast Diode		
V _{0 max}	threshold voltage	1		V
$R_{\text{0 max}}$	slope resistance *	52		$m\Omega$

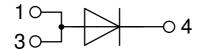


Outlines TO-263 (D2Pak-HV)



Dim.	Millimeter		Inches		
DIIII.	min	max	min	max	
Α	4.06	4.83	0.160	0.190	
A1	typ.	0.10	typ. 0	0.004	
A2	2.41		0.095		
b	0.51	0.99	0.020	0.039	
b2	1.14	1.40	0.045	0.055	
С	0.40	0.74	0.016	0.029	
c2	1.14	1.40	0.045	0.055	
D	8.38	9.40	0.330	0.370	
D1	8.00	8.89	0.315	0.350	
D2	2	2.3		0.091	
Е	9.65	10.41	0.380	0.410	
E1	6.22	8.50	0.245	0.335	
е	2,54 BSC		0,100 BSC		
e1	4.28		0.169		
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	1.02	1.68	0.040	0.066	
W	typ. 0.02	0.040	typ. 0.0008	0.002	

All dimensions conform with and/or within JEDEC standard.





Fast Diode

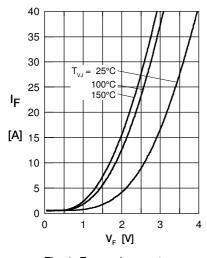


Fig. 1 Forward current I_F versus V_F

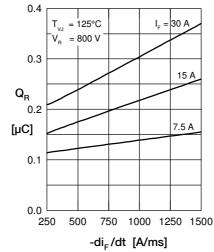


Fig. 2 Typ. reverse recov. charge $Q_{\rm r}$ versus $-{\rm di}_{\rm F}/{\rm dt}$

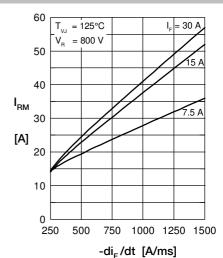


Fig. 3 Typ. peak reverse current I_{RM} versus -di_F/dt

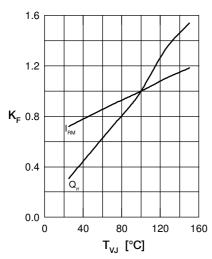


Fig. 4 Typ. dynamic parameters Q_r , I_{RM} versus T_{VJ}

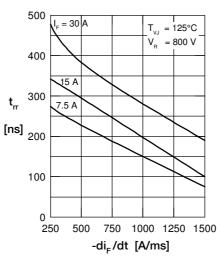


Fig. 5 Typ. recovery time t_{rr} versus $-di_{F}/dt$

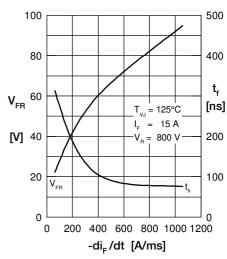


Fig. 6 Typ. peak forward voltage V_{FR} and t_{fr} versus di_F/dt

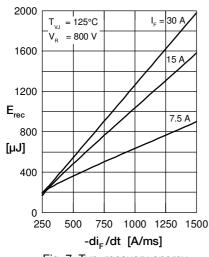


Fig. 7 Typ. recovery energy $E_{\rm rec}$ versus $-di_{\rm F}/dt$

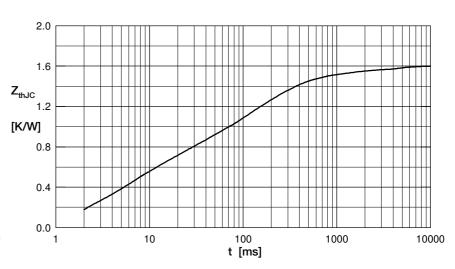


Fig. 8 Transient thermal resistance junction to case